



SOT1222-2

plastic, heatsink small outline package; 6 leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HSOP6
Package type industry code	HSOP6
Package style descriptive code	SO (small outline)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	8-6-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	20.52	-	20.57	20.62	mm
E	package width	9.91	-	9.96	10.01	mm
A	seated height	-	-	-	3.9	mm
e	nominal pitch	-	-	8	-	mm
n ₂	actual quantity of termination	-	-	6	-	



2. Package outline

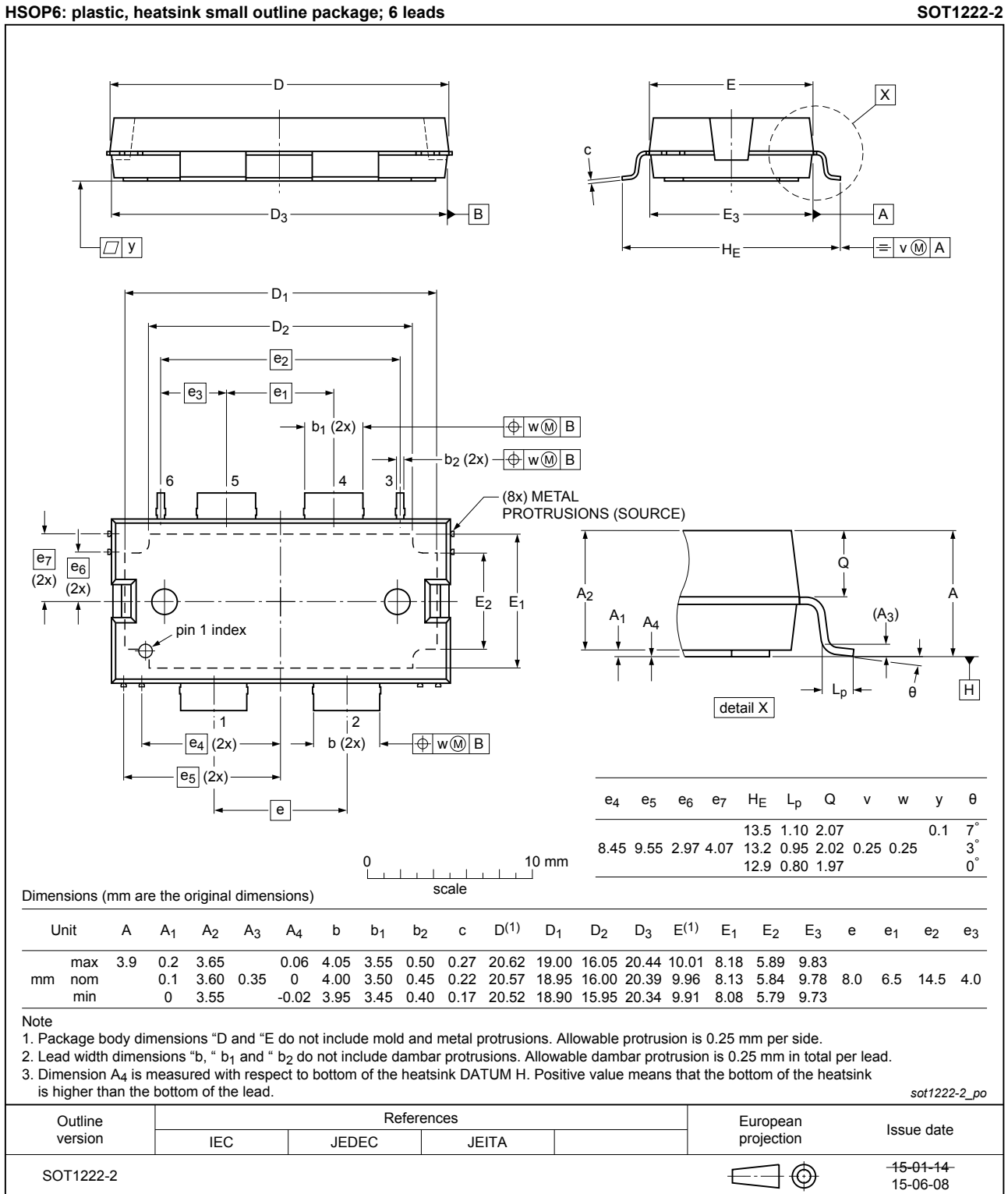


Fig. 1. Package outline HSOP6 (SOT1222-2)

3. Legal information

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